

Data and Signal Line Chokes

Series/Type: B82796C2

The following products presented in this data sheet are being withdrawn.

Ordering Code	Substitute Product		Deadline Last Orders	Last Shipments
B82796C2474N215		2015-07-10	2015-12-31	2016-03-31
B82796C2473N201		2015-07-10	2015-12-31	2016-03-31
B82796C2225N265		2015-07-10	2015-12-31	2016-03-31



Ordering Code	Substitute Product	Date of Withdrawal	Deadline Last Orders	Last Shipments
B82796C2113N201		2015-07-10	2015-12-31	2016-03-31

For further information please contact your nearest EPCOS sales office, which will also support you in selecting a suitable substitute. The addresses of our worldwide sales network are presented at www.epcos.com/sales.



Data and signal line chokes

B82796C2

Common-mode chokes, ring core

Rated voltage 42 V AC/80 V DC Rated inductance 0.011 mH to 2.2 mH Rated current 100 mA to 200 mA

Construction

- Current-compensated ring core quad choke
- Ferrite core
- Polycarbonate case (UL 94 V-0)
- Silicone potting
- Bifilar winding

Features

- Suitable for automatic insertion
- Suitable for wave soldering
- RoHS-compatible

Applications

 Suppression of asymmetrical interference coupled in on lines, whereas data signals up to some MHz can pass unaffectedly

Terminals

- Base material CuNi18Zn20
- Layer composition Ni, Sn
- Hot-dipped

Marking

Manufacturer, ordering code, date of manufacture (YWWD)

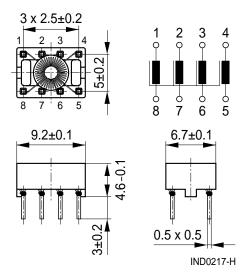
Delivery mode

Cardboard box



Common-mode chokes, ring core

Dimensional drawing and pin configuration



Tolerances to ISO 2768-M unless otherwise noted.

Dimensions in mm

Technical data and measuring conditions

Rated voltage V _R	42 V AC (50/60 Hz) / 80 V DC		
Rated temperature T _R	60 °C		
Rated current I _R	Referred to 50 Hz and rated temperature		
Rated inductance L _R	Measured with Agilent 4284A at 0.1 mA, 20 °C Measuring frequency: $L_R \le 1$ mH = 100 kHz $L_R > 1$ mH = 10 kHz Inductance is specified per winding.		
Inductance tolerance	-30%/+50% at 20 °C		
Inductance decrease ΔL/L ₀	< 10% at DC magnetic bias with I _R , 20 °C		
Stray inductance L _{stray,typ}	Measured with Agilent 4284A at 5 mA, 20 °C, typical values Measuring frequency: $L_R \le 11~\mu H = 100~kHz$ $L_R > 11~\mu H = 10~kHz$		
DC resistance R _{typ}	Measured at 20 °C, typical values, specified per winding		
Solderability (lead-free)	Sn96.5Ag3.0Cu0.5: (245 ± 5) °C, (3 ± 0.3) s Wetting of soldering area $\geq 95\%$ (to IEC 60068-2-20, test Ta)		
Resistance to soldering heat (wave soldering)	(260 ±5) °C, (10 ±1) s (to IEC 60068-2-20, test Tb)		
Climatic category	40/125/56 (to IEC 60068-1)		
Storage conditions (packaged)	–25 °C +40 °C, ≤75% RH		
Weight	Approx. 0.4 g		

Common-mode chokes, ring core

Characteristics and ordering codes

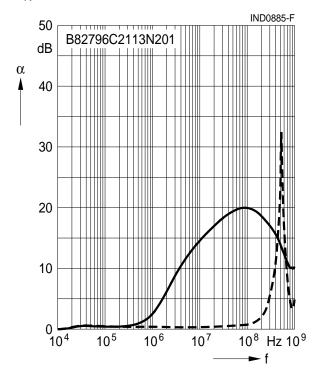
L _R	L _{stray,typ}	I _R ¹⁾	R _{typ}	V _{test}	Ordering code
mH	nH	mA	mΩ	V DC, 2 s	
0.011	70	200	60	750	B82796C2113N201
0.047	120	150	150	750	B82796C2473N201
0.47	120	100	350	750	B82796C2474N215
2.2	180	100	400	750	B82796C2225N265

Insertion loss α (typical values at $|Z| = 50 \Omega$, 20 °C)

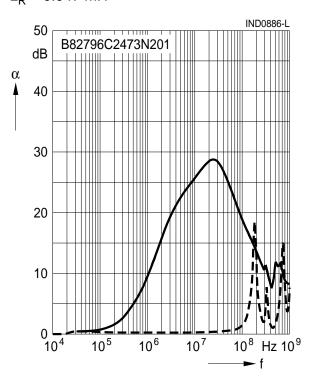
asymmetrical, all branches in parallel (common mode)

- - - - - symmetrical (differential mode)

$$L_R = 0.011 \text{ mH}$$



$$L_R = 0.047 \text{ mH}$$



¹⁾ Types with higher rated current on request.





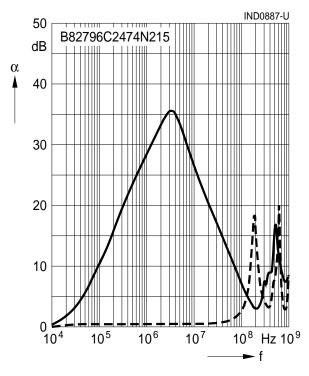
Common-mode chokes, ring core

Insertion loss α (typical values at $|Z| = 50 \Omega$, 20 °C)

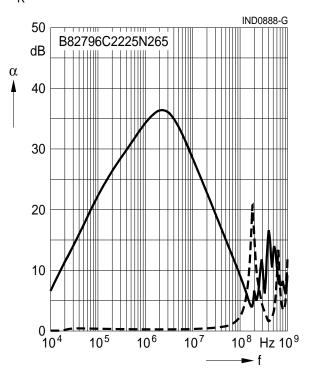
asymmetrical, all branches in parallel (common mode)

- - - - - - symmetrical (differential mode)

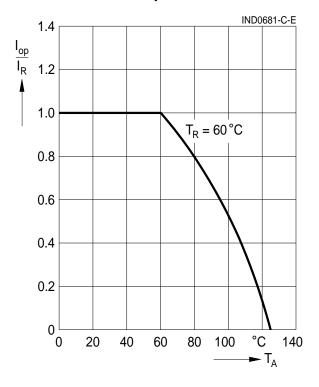
$$L_{R} = 0.47 \text{ mH}$$



$$L_R = 2.2 \text{ mH}$$



Current derating I_{op}/I_R versus ambient temperature





Cautions and warnings

- Please note the recommendations in our Inductors data book (latest edition) and in the data sheets
 - Particular attention should be paid to the derating curves given there.
 - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.
- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. In particular, it is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation.
- The following points must be observed if the components are potted in customer applications:
 - Many potting materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
 - It is necessary to check whether the potting material used attacks or destroys the wire insulation, plastics or glue.
 - The effect of the potting material can change the high-frequency behaviour of the components.
- Ferrites are sensitive to direct impact. This can cause the core material to flake, or lead to breakage of the core.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.



Important notes

The following applies to all products named in this publication:

- 1. Some parts of this publication contain statements about the suitability of our products for certain areas of application. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application. As a rule we are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether a product with the properties described in the product specification is suitable for use in a particular customer application.
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